

# MDTE Series

## Wire Wound Molded SMD Power Inductors

### Size 7020



#### FEATURES

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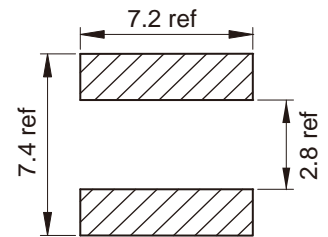
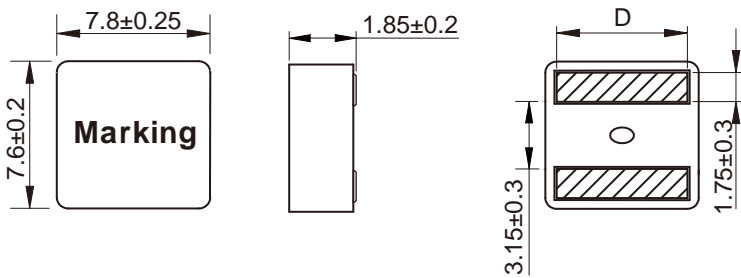
°C

#### APPLICATION

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Dimensions: [mm]

Land Pattern: [mm]



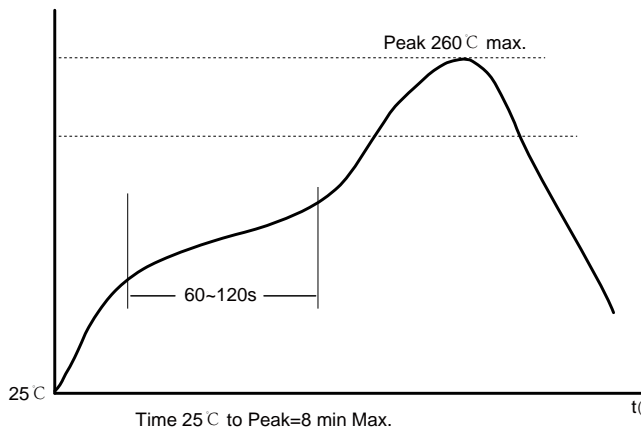
Electrical Properties:

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Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is  $\Delta T=40^{\circ}\text{C}$

## Soldering Reflow:



Peak 260

Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C: 60~90 sec.

Max temperature: 260°C.

Max time at max temperature: 10 sec.

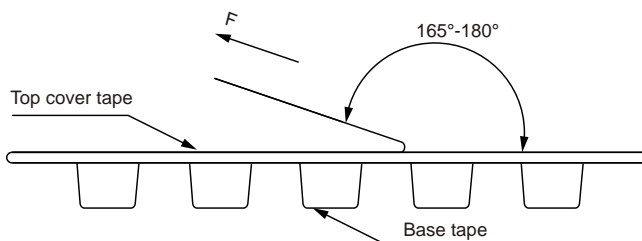
Allowed Reflow time: 2x max.

## Packaging Information:

### Tape Dimension:

| Series   | A0 (mm) | B0 (mm) | D (mm)  | P0 (mm) | P1 (mm)  | W (mm)   | K0 (mm) | E (mm)   | T (mm)    |
|----------|---------|---------|---------|---------|----------|----------|---------|----------|-----------|
| MDTE7020 | 8.2±0.1 | 8.0±0.1 | 1.5±0.1 | 4.0±0.1 | 12.0±0.1 | 16.0±0.3 | 2.3±0.1 | 1.75±0.1 | 0.35±0.05 |

### Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Reel Dimension: [mm]



Packaging Quantity: